1.0 Scope  To determine the quality of the dielectric material after etching with ferric chloride.

2.0 Applicable Documents  None.

3.0 Test Specimen  Specimen 2 in. x 2 in. X thickness of one ounce or two ounces copper clad.

4.0 Apparatus

4.1 Heated Electrical Equipment for etching the specimen.

4.2 Air Circulating Chamber capable of maintaining 80°C ± 3° (176°F).

4.3 Equipment and Chemicals needed to perform this test are as follows: Rubber or polyethylene gloves, lint free cloth, grade FFF pumice and plastic scrubbing brushes, distilled water, 10% solution oxalic acid, ferric chloride solution, methylethyl ketone, toluol, and trichlorethylene.

5.0 Procedure

5.1 Preparation of Specimen  Remove rough edges from the specimen by sanding or other suitable means.

5.2 Etching  Etch specimens with vigorous agitation for the minimum time in 42° BAUME ferric chloride solution monitored at 30°C ± 6° (86°F). After removal of the copper, immediately wash the specimen with running tap water for 2 to 5 minutes and keep the specimen from drying until the specimen is placed in the chamber. Immerse specimens in a 10% solution of oxalic acid in distilled water at 25°C ± 8° (77°F) for 15 to 20 minutes providing gentle circulation of the oxalic acid solution during this period. Flush the specimens with tap water for 2 to 5 minutes, then scrub the specimens with pumice to remove resist. Wipe the resist off with a lint free cloth moistened with a suitable solvent. Scrub the specimen with a plastic bristled brush under running tap water for 2 to 5 minutes, then rinse for 30 minutes. Rinse the specimen again in distilled water.

5.3 Condition  Dry the specimens for 1 hour in a chamber maintained at 80°C (176°F). If specimens are for electrical tests, handle only with rubber or polyethylene gloves.

5.4 Evaluation of Test  Examine specimens for white deposits or other surface contaminants, loss of surface resin softness, delamination, blistering or measling. Clad specimens also should be evaluated for blisters or delamination of the copper foil.

6.0 Notes

6.1  If the etching time exceeds 15 minutes for 1 ounce copper or 30 minutes for 2 ounces copper, renew the etching solution.

6.2  Oxalic acid is very toxic and extreme caution should be exercised.

6.3  The time to produce a clean pattern with a minimum undercutting is approximately 7 minutes for 1 ounce copper, and 15 minutes for 2 ounce copper using a fresh solution.